

客 户

CUSTOMER

Z133

承 認 書
SPECIFICATION FOR
APPROVAL

客 户 品 名

料 号

CUSTOMER NAME.

PART NO.

本公司品名

料 号

OURS PART NAME.

VECM7060-701-2PL

PART NO.

FIA09070-01

工程出图

ENGINEERING DRAWING

發行

檢查

承認

MADE

CHECKED

APPROVED

日期

DATE: 2019 年 07 月 29 日

承認印

CUSTOMER APPROVE

采 购

工 程

品 保

承认结果：请予以认证，提出修改意见或确认后签回，如未签回下订单，则是视为默认。

所签回的传真件及复印件均视为具有法律效力



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承 认 书 番 号

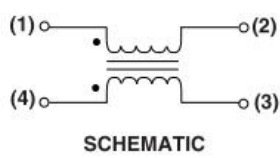
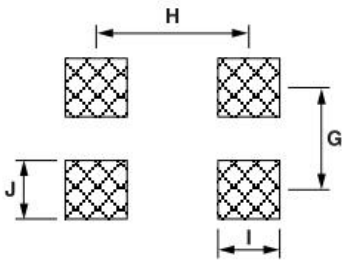
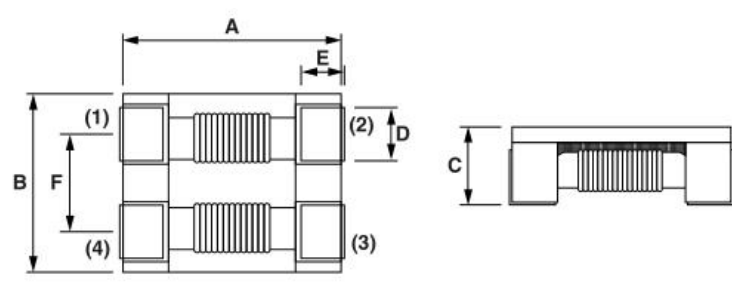
SPEC NO. VE-Z133-20190729001

一. 产品实物图
Product physical map



二.产品尺寸图：(mm)

Dimensions in (mm)



注：绕线均匀平整无交叉。

A	B	C	D	E	F	G	H	I	J
7.0±0.3	6.0±0.3	4.0Max	1.6±0.3	1.8±0.3	3.0Typ	3.0Ref	6.5Ref	2.5Ref	1.6Ref

四. 绕组结构
WINDING

WINDING	START	FINISH	WIRE (φ)	COLORE	TURNS	REMARK
N1	1	2				
N2	4	3				

深圳市千代源电子有限公司 SHEN ZHEN VOLUME SOURCE ELECTRONICS CO., LTD.	APPROVALS		DATE		
	DRAWN BY	卢永汉		REV	A 0
	CHECKED BY			DATE	2019-07-24
	APPROVED BY			PAGE	2 / 5

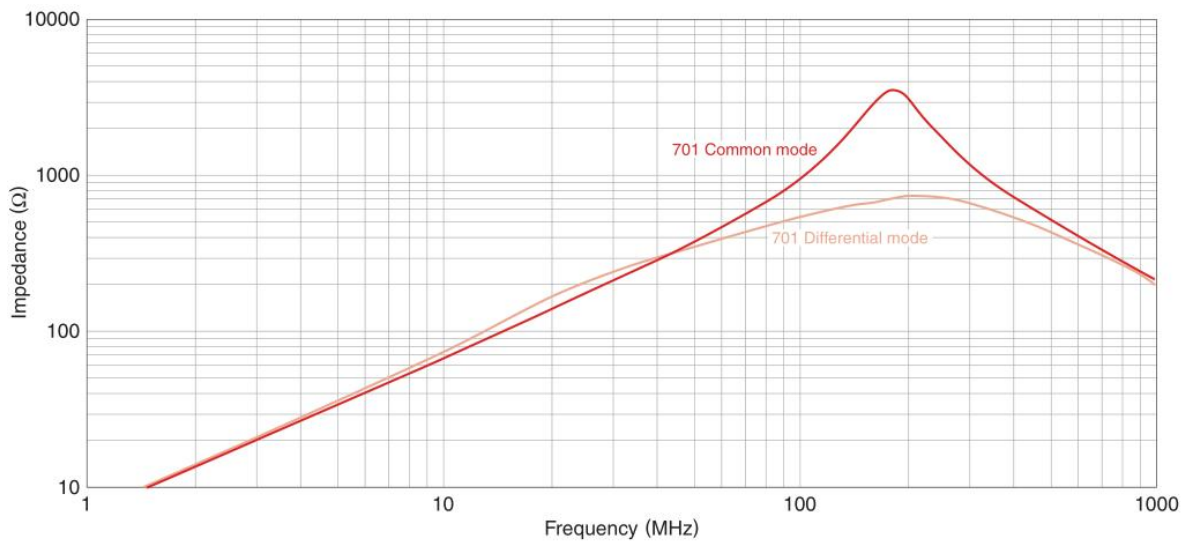
五：规格

Specifications

产品种类 Product Category	Common-mode choke/filter	零件号别名 Part number alias	VECM7060-701-2PL
端接类型 End connection type	SMD/SMT	应用 application	LAN’ s, telephones, personal computers
阻抗 Impedance	700 Ω	磁芯型号 Core type	CM7060
容差 tolerance	25%	测试条件 Test conditions	100MHz
最大直流电流 Maximum DC Current	4. 0A	最大直流电阻 Maximum DC Resistance	15 mΩ
RATED VOLTAGE MAX. (V _{DC}) 额定电压 最大值（直流电压）	80	储存温度 Storage temperature	-5℃～+30℃（相对湿度：20%-75%）
INSULATION RESISTANCE MIN. (mΩ) 绝缘 最小电阻（mΩ）	10		
工作温度范围 Operating Temperature Range	-25℃～+85℃		
封装 encapsulation	Mouse Reel		
包装数量 Packing Quantity	1000 PCS		
子类别 Subcategories	Inductors, Chokes & Coils		
单位重量 Unit weight (typ.)	0. 55g		

六. 阻抗频率特性

Impedance frequency characteristics



七. 推荐的焊接技术

Recommended Soldering Technologies

1. Re-flowing Profile:

- △ Preheat condition: 150 ~200°C/60~120sec.
- △ Allowed time above 217°C: 60~90sec.
- △ Max temp: 260°C
- △ Max time at max temp: 5sec.
- Solder paste: Sn/3.0Ag/0.5Cu
- △ Allowed Reflow time: 2x max
- Please refer to **Fig. 1-1**.

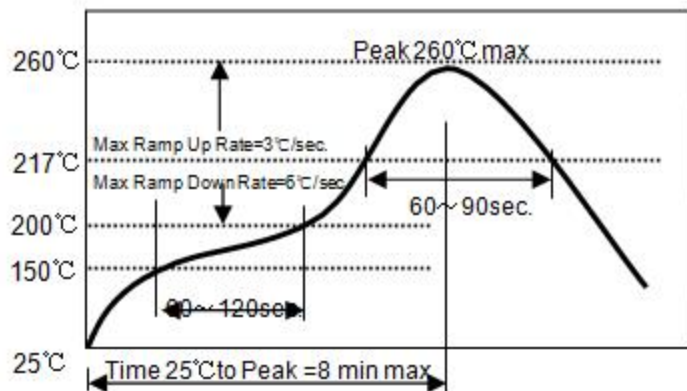


Fig. 1-1

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

2. Iron Soldering Profile:

- △ Iron soldering power: Max. 30W
- △ Pre-heating: 150°C/60sec.
- △ Soldering Tip temperature: 350°C Max.
- △ Soldering time: 3sec. Max.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Max.1 times for iron soldering
- Please refer to **Fig. 2-1**.

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]

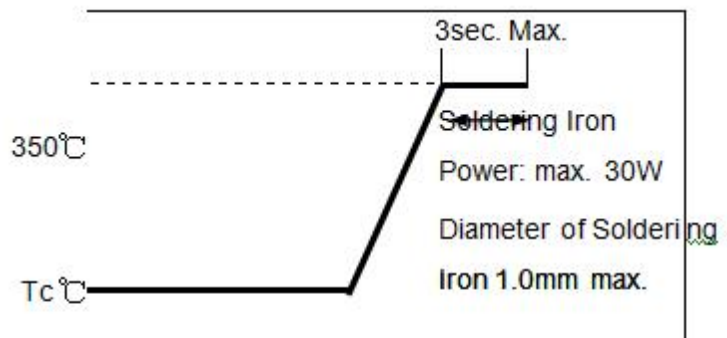
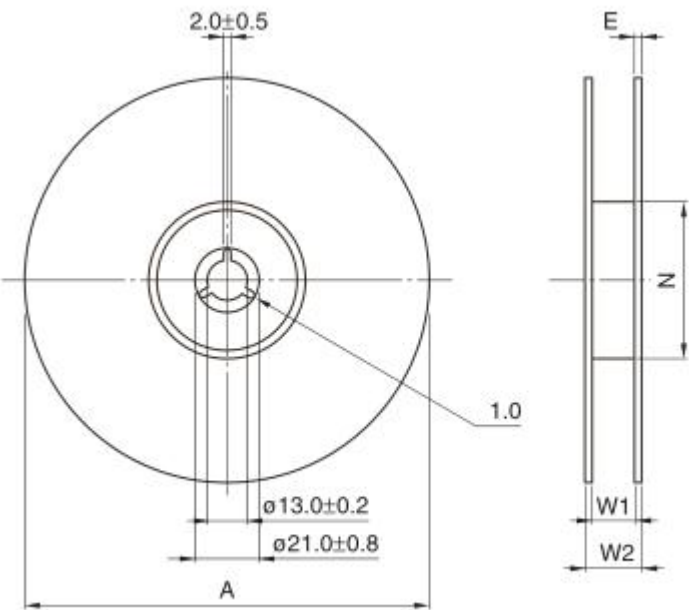


Fig. 2-1

八. 包装形式

Packaging Form

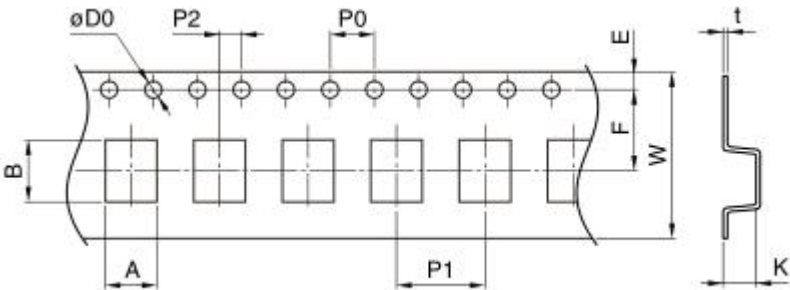
1. 卷筒尺寸



Dimensions in (mm)

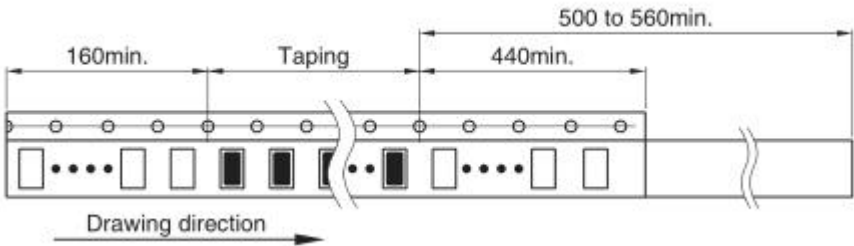
A	W1	W2	N	E
$\Phi 330 \pm 2.0$	$16.5 + 2/0$	22.5 ± 0.5	100 ± 1.0	2.0Typ

2. 编带尺寸



Dimensions in (mm)

A	B	$\Phi D0$	E	F	P0
7.6 ± 0.2	9.6 ± 0.2	$1.5 + 0.1/0$	1.75 ± 0.1	7.5 ± 0.1	4.0 ± 0.1
P1	P2	W	K	t	
12.0 ± 0.1	2.0 ± 0.1	16.0 ± 0.3	4.6 ± 0.1	0.4 ± 0.05	



Dimensions in (mm)